MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

CERAMIC DIP 40, 103.63x15.49
CASE 125BN
ISSUE O

DATE 03 JUL 2014

Dimensions in: Inches [mm]

NOTES:
1. COVER GLASS IS VISUALLY ALIGNED
   OVER DIE — NO GUARANTEE OF
   LOCATION ACCURACY.

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SEE DETAIL A
SEE NOTE 1
SEE DETAIL B

CENTER OF IMAGE AREA

DETAIL A
A 0.372±0.010 [9.45±0.25]
PATTERN 8002 CENTERLINE

CENTERLINE OF GREEN ELEMENTS

Pad 1 Indicator

DETAIL B
B 0.101±0.010 [2.57±0.25]
CENTERLINE OF GREEN ELEMENTS

EDGE OF DIE TO OUTER EDGE OF BOND PAD

0.099±0.010 [2.52±.25] TOP OF IMAGER TO TOP OF PACKAGE

0.091±0.010 [2.31±.25] TOP OF IMAGER TO BOTTOM OF PACKAGE

NOTES:
1. DIE LOCATION SPECIFIED BY DETAILS "A" AND "B".
2. CENTER OF IMAGE AREA IS OFFSET FROM CENTER OF PACKAGE BY (0.00, 0.03) mm NOMINAL.
3. DIE IS VISUALLY ALIGNED WITHIN ±0.75° OF ANY PACKAGE CAVITY EDGE.
4. DIE CENTERED HORIZONTALLY ON D/A PAD.

Dimensions in: Inches [mm]